



- MATERIAL: HOUSING – HTN MOLDING COMPOUND, UL 94V-0, COLOR: BLACK
 TERMINAL – 0.36 [.014] THICK PHOS BRONZE PLATED WITH 1.27 μm [.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81 μm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27 μm [.000050] MINIMUM THICK NICKEL UNDERPLATE.
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- BULK PACKAGED IN A TRAY

5569118-1
 PART NUMBER

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|--|----------------------|--|--|---------------------------------------|
| THIS DRAWING IS A CONTROLLED DOCUMENT. | | DIN A. FERNANDEZ-DOCKS 10JUN2005 | Tyco Electronics Corporation Harrisburg, PA 17105-3608 | |
| DIMENSIONS: mm [INCHES] | | CHK J. WESTMAN 10JUN2005 | Tyco Electronics | |
| TOLERANCES UNLESS OTHERWISE SPECIFIED: | | APVD S. FLICKINGER 10JUN2005 | NAME MODULAR JACK ASSEMBLY, 8 POSITION, LOW PROFILE, RIGHT ANGLE, KEYED WITHOUT PANEL STOPS | |
| 0 PLC ± - 1 PLC ± - 2 PLC ± - 3 PLC ± 0.13 4 PLC ± - ANGLES ± - | | PRODUCT SPEC 108-1163 | APPLICATION SPEC 114-2048 | |
| MATERIAL SEE NOTE 1 | FINISH SEE NOTE 1 | WEIGHT - | SIZE A1 | CAGE CODE DRAWING NO 00779 5569118 |
| CUSTOMER DRAWING | | SCALE 4:1 | SHEET 1 of 1 | REV B |

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)